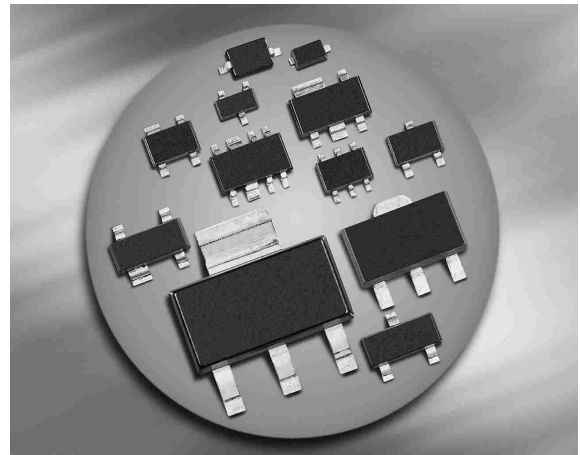


**Ultra-Low Capacitance ESD Diode Array**

- Rail-to-rail diodes with internal TVS diode
- ESD / transient protection of four I/O lines and one Vcc line exceeding:
  - IEC61000-4-2 (ESD):  $\pm 15$  kV (contact)
  - IEC61000-4-4 (EFT): 2.5 kV / 50 A (5/50 ns)
  - IEC61000-4-5 (surge): 3 A (8/20  $\mu$ s)
- Reverse working voltage data lines: 5.3 V max.
- Reverse working voltage Vcc: 6 V max.
- Very low capacitance: 0.4 pF typ.
- Very low reverse current < 10 nA typ.
- Very low clamping voltage:
  - 12 V typ. at positive transients
  - 4 V typ. at negative transients
- Pb-free (RoHS compliant) package

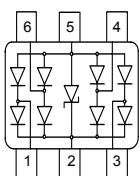


**Applications**

- USB 2.0 ports and future USB 3.0 ports
- Ethernet port: 10/100/1000 Mb/s
- IEEE 1394 FireWire ports
- Mobile communications e.g. high-speed SIM card protection
- Consumer products (STB, DVD, DSC, DVC...)
- Notebooks and desktop computers, peripherals



**ESD5V3U4RRS**



Type	Package	Configuration	Marking
ESD5V3U4RRS	SOT363	6 pins, uni-directional	E8s

**Maximum Ratings** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Value	Unit
ESD contact discharge <sup>1)</sup>	$V_{\text{ESD}}$	15	kV
Peak pulse current ( $t_p = 8 / 20 \mu\text{s}$ ) <sup>2)</sup>	$I_{\text{pp}}$	3	A
Peak pulse power ( $t_p = 8 / 20 \mu\text{s}$ ) <sup>2)</sup>	$P_{\text{pk}}$	50	W
Operating temperature range	$T_{\text{op}}$	-55...125	°C
Storage temperature	$T_{\text{stg}}$	-65...150	

**Electrical Characteristics** at  $T_A = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Values			Unit
		min.	typ.	max.	
<b>Characteristics</b> <sup>3)</sup>					
Reverse working voltage I/O pin <sup>4)</sup> to pin 5 pin 2 to pin 5	$V_{\text{RWM}}$	-	-	5.3 6	V
Breakdown voltage $I_{\text{(BR)}} = 1 \text{ mA}$ , any pin to pin 5	$V_{\text{(BR)}}$	6.3	-	-	
Reverse current $V_{\text{R}} = 5.3 \text{ V}$ , any pin to pin 5	$I_{\text{R}}$	-	< 10	100	nA
Clamping voltage $I_{\text{PP}} = 1 \text{ A}$ , $t_p = 8/20 \mu\text{s}$ <sup>2)</sup> , any pin to pin 5 $I_{\text{PP}} = 3 \text{ A}$ , $t_p = 8/20 \mu\text{s}$ <sup>2)</sup> , any pin to pin 5	$V_{\text{CL}}$	-	10 12	13 15	V
Forward clamping voltage $I_{\text{PP}} = 1 \text{ A}$ , $t_p = 8/20 \mu\text{s}$ <sup>2)</sup> , any pin to pin 5 $I_{\text{PP}} = 3 \text{ A}$ , $t_p = 8/20 \mu\text{s}$ <sup>2)</sup> , any pin to pin 5	$V_{\text{FC}}$	-	2 4	4 6	
Line capacitance <sup>5)4)</sup> $V_{\text{R}} = 0 \text{ V}$ , $f = 1 \text{ MHz}$ , any I/O pin to pin 5	$C_{\text{T}}$	-	0.4	0.6	pF
Dynamic resistance <sup>6)</sup>	$R_{\text{D}}$	-	-	-	-

<sup>1)</sup>  $V_{\text{ESD}}$  according to IEC61000-4-2

<sup>2)</sup>  $I_{\text{pp}}$  according to IEC61000-4-5

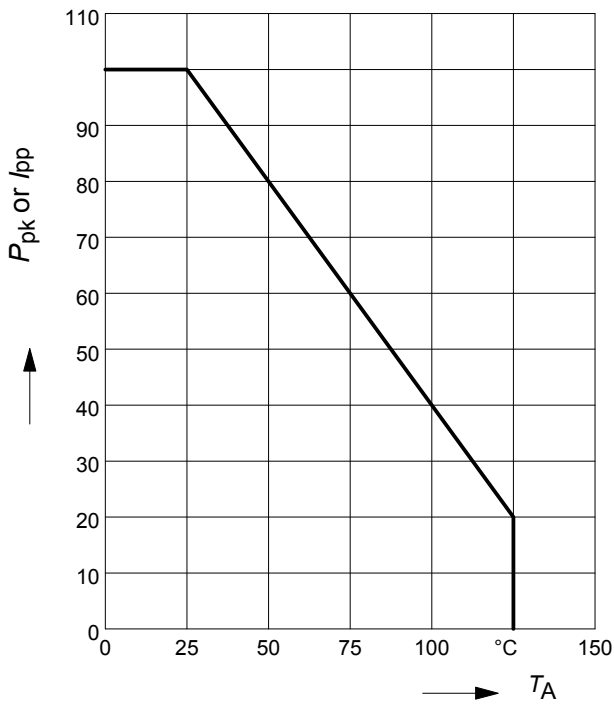
<sup>3)</sup> It is strongly recommended that pin 5 is connected to ground for proper functionality.

<sup>4)</sup> I/O pins are pin 1, 3, 4, 6

<sup>5)</sup> Total capacitance line to ground

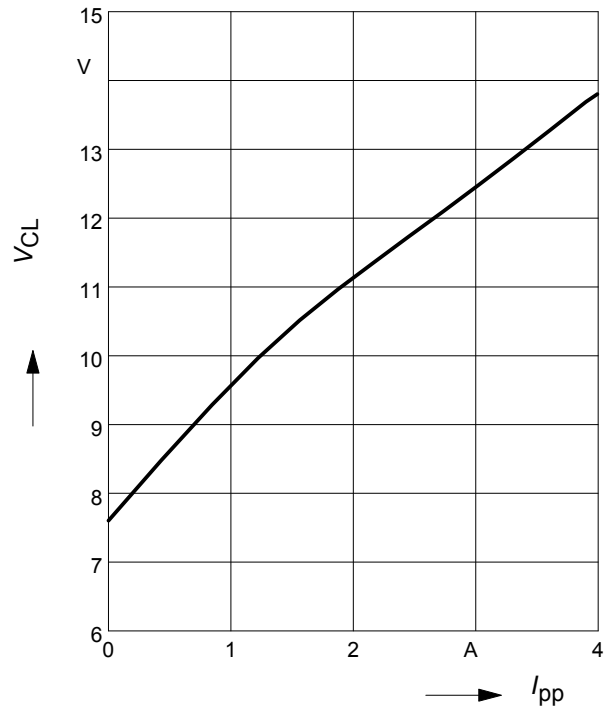
<sup>6)</sup> according to TLP tests

**Power derating curve  $P_{pk} = f(T_A)$**



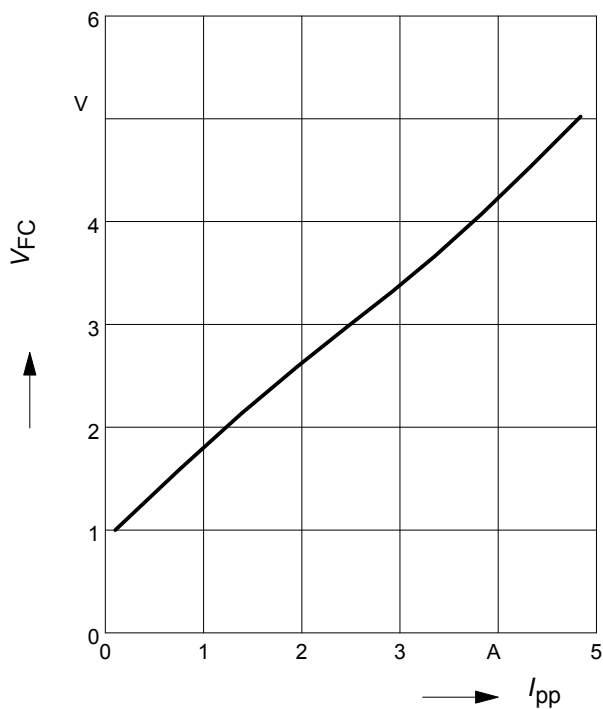
**Clamping voltage,  $V_{cl} = f(I_{pp})$**

$t_p = 8 / 20 \mu s$



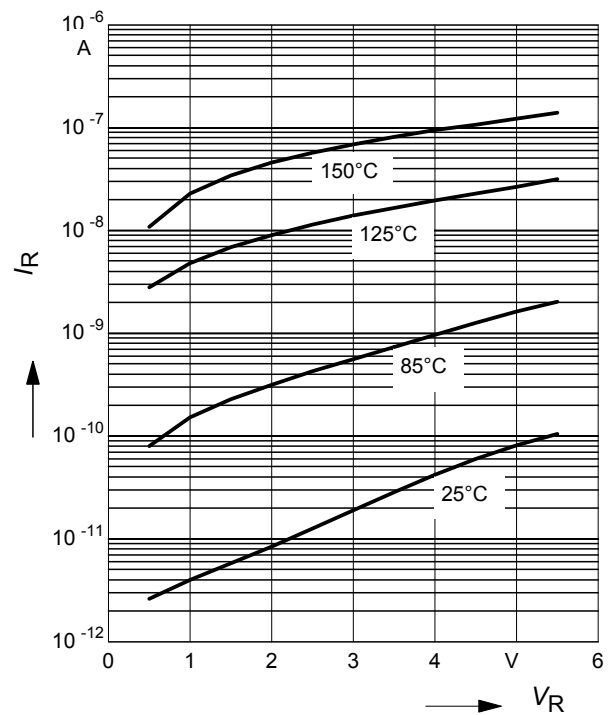
**Forward clamping voltage  $V_{FC} = f(I_{PP})$**

$t_p = 8 / 20 \mu s$



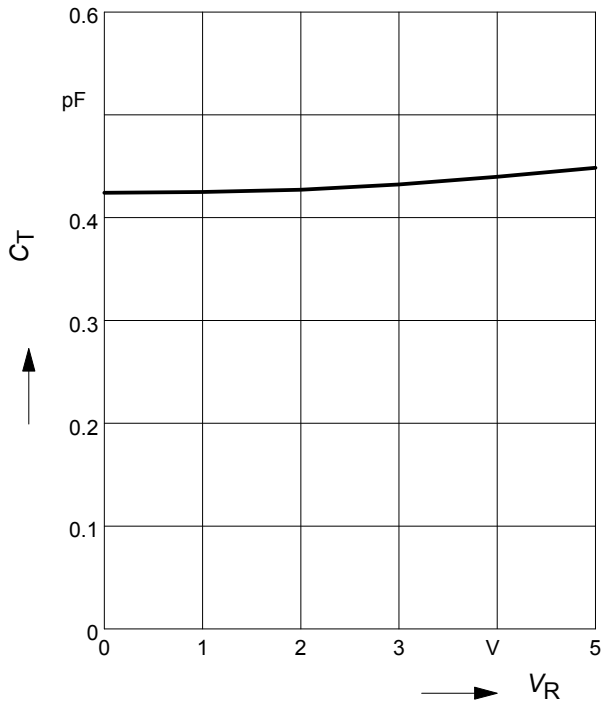
**Reverse current  $I_R = f(V_R)$**

$T_A = \text{Parameter}$



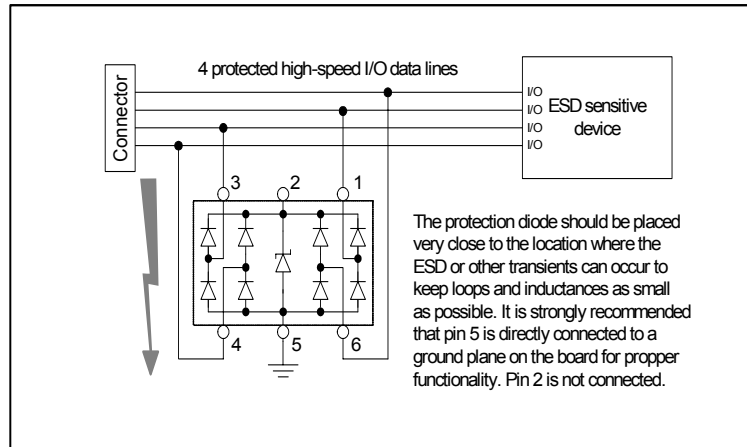
Diode capacitance  $C_T = f(V_R)$

$f = 1\text{MHz}$



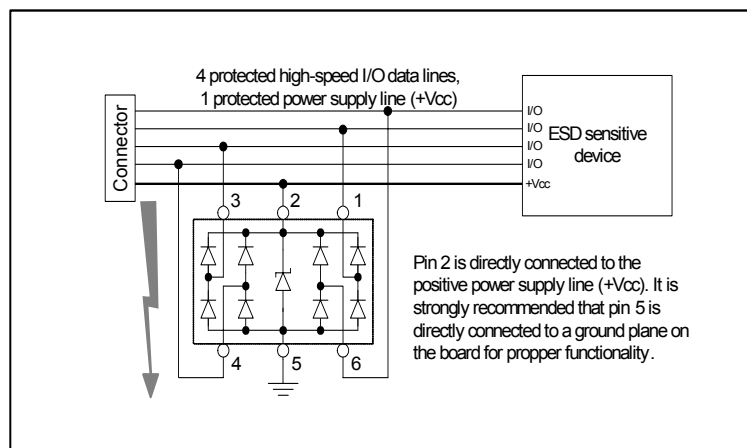
**Application example ESD5V3U4RRS**

4 data lines, uni-directional

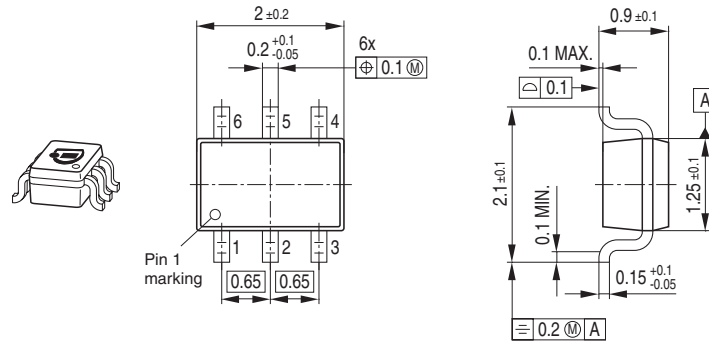


**Application example ESD5V3U4RRS**

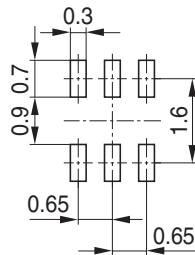
4 data lines and 1 power supply line, uni-directional



Package Outline

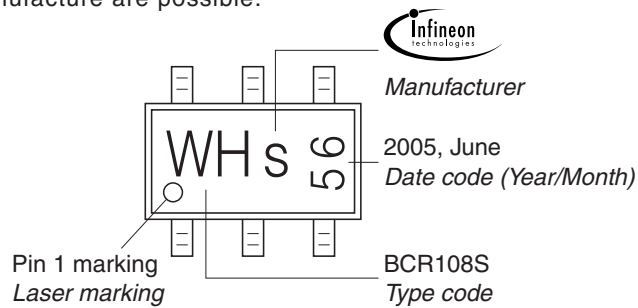


Foot Print



Marking Layout (Example)

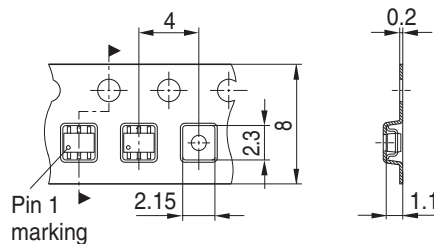
Small variations in positioning of Date code, Type code and Manufacture are possible.



Standard Packing

Reel  $\varnothing$ 180 mm = 3.000 Pieces/Reel  
 Reel  $\varnothing$ 330 mm = 10.000 Pieces/Reel

For symmetric types no defined Pin 1 orientation in reel.



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